ASSOCIATION OF ELECTRONICS	© Copyright 2005.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				ials and Mfc Information				
upplier l	Information													
Company name*			Company unique ID			J	Unique ID Authority				Response Date*			
nsemi										2025-05-14				
Contact Nar	me	Title - Contact			I	Phone - Contact*				Email - Contact*				
Product-En	v-Stewards		Product Enviro Compliance]	NA				Product-Env-Stewards@onsemi.com			
uthorized	Representative*	Title - Representative			I	Phone - Representative*				Email - Representative*				
Product-En	v-Stewards	Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com				
I	Requester Item Number		Mfr Item Number Mfr Item Name				Effective Date		Manufacturing Site	W	eight*	UOM	Unit Type	
		FGB20N60SFD-F085 FS P TO263 2		FS P TO263 20A 6	A 600V AUTO		2025-05-14		C	СРА		85.098	mg	Each
	curing Proccess Inform								·					·
ž ž			Terminal Base Alloy J-STD-020 MSL		Rating	Peak Process Body Tempera		T *			e Numbe	er of Reflow Cyc	cles	
N	Matte Tin (Sn) - annealed		CU Alloy	1			260		C	30	seconds	3		
omments														
vel 1 - max	ximum time at peak tempera	ture during sol	ldering is 10-3	0 seconds										
or more in	formation regarding materia	al composition	please refer to	page 3										

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Priective 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Standard Terms and Conditions of Sale applicable to su										
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature Ra	astislav Drska	-En								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	12.3	mg	Supplier	Silicon (Si)	7440-21-3		12.3	mg
Die Attach Solder	7.33	mg	Supplier	Silver (Ag)	7440-22-4		0.1832	mg
			A	Lead (Pb)	7439-92-1	7a	6.7803	mg
			Supplier	Tin (Sn)	7440-31-5		0.3665	mg
Lead Frame	860.318		Supplier	Tin (Sn)	7440-31-5		1.0324	mg
			В	Nickel (Ni)	7440-02-0		0.4302	mg
			Supplier	Copper (Cu)	7440-50-8		858.8555	mg
Mold Compound-Black	595.0		Supplier	Brominated Epoxy Resin-2	68541-56-0		14.875	mg
			Supplier	Other Epoxy resins	Proprietary Data		17.85	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		11.9	mg
			Supplier	Carbon Black (C)	1333-86-4		2.975	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		517.65	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		29.75	mg
Plating	5.52	mg	Supplier	Tin (Sn)	7440-31-5		5.52	mg
Wire Bond - Al	4.63	mg	Supplier	Aluminum (Al)	7429-90-5		4.63	mg